SLOVENSKI STANDARD
SIST EN 62779-3:2016

01-september-2016

Polprevodniški elementi - Polprevodniški vmesnik za komuniciranje človeškega telesa - 3. del: Funkcijski tip in pogoji za njegovo delovanje (IEC 62779-3:2016)

Semiconductor devices - Semiconductor interface for human body communication - Part 3: Functional type and its operational conditions (IEC 62779-3:2016)

Ta slovenski standard je istoveten z: EN 62779-3:2016

ICS:

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general

SIST EN 62779-3:2016 **en**

EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN 62779-3

June 2016

ICS 31.080.01

English Version

Semiconductor devices - Semiconductor interface for human body communication - Part 3: Functional type and its operational conditions (IEC 62779-3:2016)

Dispositifs à semiconducteurs - Interface à semiconducteurs pour les communications via le corps humain - Partie 3: Type fonctionnel et ses conditions d'utilisation (IEC 62779-3:2016)

Halbleiterbauelemente - Halbleiterschnittstelle zur Kommunikation über den menschlichen Körper - Teil 3: Funktionstyp und seine Betriebsbedingungen (IEC 62779-3:2016)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

European foreword

The text of document 47/2282/FDIS, future edition 1 of IEC 62779-3, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62779-3:2016.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2017-02-28
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2019-05-31

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The text of the International Standard IEC 62779-3:2016 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following note has to be added for the standard indicated :

IEC 62779	NOTE	Harmonized in EN 62779 series.

IEC 62779-3

Edition 1.0 2016-04

INTERNATIONAL STANDARD

NORME INTERNATIONALE

colour inside

Semiconductor devices – Semiconductor interface for human body communication – Part 3: Functional type and its operational conditions

Dispositifs à semiconducteurs – Interface à semiconducteurs pour les communications via le corps humain – Partie 3: Type fonctionnel et ses conditions d’utilisation

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SEMICONDUCTOR DEVICES – SEMICONDUCTOR INTERFACE FOR HUMAN BODY COMMUNICATION –

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FOREWORD

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International Standard IEC 62779-3 has been prepared by IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/2282/FDIS	47/2292/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62779 series, published under the general title *Semiconductor devices – Semiconductor interface for human body communication,* can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

The IEC 62779 series is composed of three parts as follows:

- IEC 62779-1 defines general requirements of a semiconductor interface for human body communication. It includes general and functional specifications of the interface.
- IEC 62779-2 defines a measurement method on electrical performances of an electrode that constructs a semiconductor interface for human body communication.
- IEC 62779-3 defines functional type of a semiconductor interface for human body communication, and operational conditions of the interface.

IEC 60748-4 gives requirements on interface integrated circuits for semiconductor devices. Especially, Chapter III, Section 7 in this standard is applied to interface circuits for a communication network using a general channel, such as wire or wireless. However, a channel for HBC is the human body whose channel properties, such as signal loss and delay profile, are different from the general channel, so the Chapter III, Section 7 cannot be applied to an interface for HBC. Furthermore, a standard on a communication protocol for body area network (BAN) – IEEE 802.15.6 (IEEE Std 802.15.6-2012), which includes a communication protocol for HBC was published in 2012. A common interface for HBC should be defined to secure communication compatibility between various devices that are implemented on/inside the human body or embedded in peripheral equipments.